

**Amendments to the Claims:**

This listing of claims will replace all prior versions, and listings of claims in the application:

**Listing of Claims:**

Please amend the claims as follows:

1.-9. (Cancelled)

10. (Currently Amended) A resin composition, capable of being employed for forming a resin layer of a resin-attached metal foil, comprising:

a cyanate resin and/or a prepolymer thereof;  
an epoxy resin substantially containing no halogen atom;  
a phenoxy resin substantially containing no halogen atom;  
an imidazole compound; and  
an inorganic filler,

wherein said cyanate resin is present in a range of from 5 to 50 %wt. of said resin composition,

said epoxy resin is present in a range of from 5 to 50 %wt. of said resin composition,

said phenoxy resin is present in a range of from 1 to 40 %wt. of said resin composition,

said imidazole compound is present in a range of from 0.05 to 5 %wt. of the combination of the said cyanate resin and said epoxy resin and,

said inorganic filler is present in a range of from 20 to 70 %wt. of said resin composition.

11. (Currently Amended) A resin composition, capable of being employed for forming an insulating sheet of a base material-attached insulating sheet, comprising:

a cyanate resin and/or a prepolymer thereof;  
an epoxy resin substantially containing no halogen atom;  
a phenoxy resin substantially containing no halogen atom;  
an imidazole compound; and  
an inorganic filler,

wherein said cyanate resin is present in a range of from 5 to 50 %wt. of said resin composition,

said epoxy resin is present in a range of from 5 to 50 %wt. of said resin composition,

said phenoxy resin is present in a range of from 1 to 40 %wt. of said resin composition,

said imidazole compound is present in a range of from 0.05 to 5 %wt. of the combination of the said cyanate resin and said epoxy resin and,  
said inorganic filler is present in a range of from 20 to 70 %wt. of said resin composition..

12. (Previously Presented) The resin composition according to claim 10, wherein said cyanate resin is a novolac cyanate resin.

13. (Previously Presented) The resin composition according to claim 11, wherein said cyanate resin is a novolac cyanate resin.

14. (Previously Presented) The resin composition according to claim 10, wherein said epoxy resin is an aryl alkylene epoxy resin.

15. (Previously Presented) The resin composition according to claim 11, wherein said epoxy resin is an aryl alkylene epoxy resin.

16. (Previously Presented) The resin composition according to claim 10, wherein said imidazole compound has two or more functional groups selected from a group consisting of aliphatic hydrocarbon group, aromatic hydrocarbon group, hydroxyalkyl group and cyano alkyl group.

17. (Previously Presented) The resin composition according to claim 11, wherein said imidazole compound has two or more functional groups selected from a group consisting of aliphatic hydrocarbon group, aromatic hydrocarbon group, hydroxyalkyl group and cyano alkyl group.

18. (Previously Presented) A resin-attached metal foil, formed by cladding a metal foil with the resin composition according to claim 10.

19. (Previously Presented) A multiple-layered printed wiring board, formed by laying the resin-attached metal foil(s) according to claim 18 on a single side or both sides of an internal layer circuit board and hot pressure forming thereof.

20. (Previously Presented) A base material-attached insulating sheet, formed by cladding an insulating base material with the resin composition according to claim 11.

21. (Previously Presented) A multiple-layered printed wiring board, formed by laying the base material-attached insulating sheet(s) according to claim 20 on a single side or both sides of an internal layer circuit board and hot pressure forming thereof.